

PMP4391\_RevA Bom

Count	Refdes	Value	Description	Size	Part Number	MFR
1	C3	C0805,1uf	CAP CER 1UF 50V 20% X7R	0805	Std	Murata
1	C4	C1206,680pf	CAP CER 680PF 630V 5% U2J 1206	1206	Std	TDK
2	C1 C2	6.8uF	CAP ALUM 6.8UF 400V 20% RADIAL	8*10.8mm	400AX6.8M8X10.8	RubyCon
1	C5	47pf	CAP CER 47PF 1KV 5% U2J 1206	1206	GRM31A7U3A470JW31D	Murata
1	C9	1nf	CAP CER 1nF 100V 20% X7R 0603	0603	Std	Murata
1	C10	NA				
1	BD1	MDB6S	IC BRIDGE DIODE 600V 4-MICRODIP	4-SMD	MDB6S	Fairchild
1	D1	DFLR1600-7	DIODE STD REC 1A 600V POWERDI123	PowerDI™ 123	DFLR1600-7	Diodes
1	D2	BAS21AHT1G	DIODE SWITCHING 250V 0.2A SOD323	SOD323	BAS21AHT1G	Onsemi
1	D6	SBR10U45SP5-13	DIODE BYPASS 10A 45V POWERDI5	PowerDI™ 5	SBR10U45SP5-13	Diodes
1	D5	NA				
1	F1	RST 500AMMO	FUSE SLOW 250VAC 500MA RADIAL		RST 500AMMO	Bel Fuse Inc
2	C7 C8	270uf	CAP ALUM 270UF 6.3V 20% RADIAL	5*8mm	RF80J271MDN1PX	Nichicon
1	L1	470uH	CHOKE RF 470UH 170MA AXIAL		7447462471	wurth
1	L2	Bead			MPZ2012S601A	TDK
1	R9	NA	Resistor, Chip, 1/10W, 1%	0603	STD	Yageo
1	R12	R0603,82k	Resistor, Chip, 1/10W, 1%	0603	STD	Yageo
1	R8	R00805,10	Resistor, Chip, 1/8W, 1%	0805	STD	Yageo
2	R6	R0603,30K	Resistor, Chip, 1/10W, 1%	0603	STD	Yageo
1	R11	R0603,22	Resistor, Chip, 1/10W, 1%	0603	STD	Yageo
1	R13	R0805,1.3	Resistor, Chip, 1/8W, 1%	0805	STD	Yageo
1	R3	R0805,2.7K	Resistor, Chip, 1/8W, 1%	0805	STD	Yageo
1	R1	R1206,680	Resistor, Chip, 1/4W, 1%	1206	STD	Yageo
2	R15,R16	R0805_1%,4.7M	Resistor, Chip, 1/10W, 1%	0805	STD	Yageo
1	R10	R0603,1.2k	Resistor, Chip, 1/10W, 1%	0603	STD	Yageo
1	R7	NA	Resistor, Chip, 1/10W, 1%	0603	STD	Yageo
2	R5,R4	R1206,300K	Resistor, Chip, 1/4W, 1%	1206	STD	Yageo
1	USB1	NA				
1	R2	NA	NTC			
1	T1	EPC17S	Transformer, Discontinuous Mode Flyback, ±5%		EPC17S	
1	Q1	3DD13005ED-R-R-B-A	TRANS NPN 400V FAST SW DPAK	Dpak	3DD13005ED-R-R-B-A	吉林华微
1	U1	UCC28722	Constant-Voltage, Constant-Current PWM With Pri6SOT-23		UCC28722	TI

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